

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-7. (canceled)

8. (currently amended) A semiconductor device having a mounting surface attached to a circuit board, the device comprising:

plural reinforcing pads on said mounting surface of said semiconductor device that are each adjacent to a respective corner of said mounting surface; and

plural first solder balls on each of said reinforcing pads, each of said plural first solder balls separately attaching the semiconductor device to the circuit board,

wherein said reinforcing pads each have a respective periphery adjacent to each respective one of said plural ones of said first solder balls that, when seen in a plan view of said mounting surface, is at least semicircular.

9. (previously presented) The device of claim 8, wherein said reinforcing pads are generally X-shaped and have four of said first solder balls thereon, each of said four first solder balls being at a respective distal end thereof.

10. (previously presented) The device of claim 8, wherein said reinforcing pads are generally V-shaped and have at least two of said first solder balls thereon, each of said at least two first solder balls being at a respective distal end thereof.

11. (previously presented) The device of claim 8, further comprising plural second solder balls on said mounting surface and not on said reinforcing pads.

12. (previously presented) The device of claim 8, wherein said periphery of said reinforcing pads adjacent to said plural ones of said first solder balls, when seen in the plan view of said mounting surface, is no more than semicircular.

13. (currently amended) A semiconductor device having a mounting surface attached to a circuit board, the device comprising:

plural reinforcing pads on said mounting surface of said semiconductor device that are each adjacent to a respective corner of said mounting surface; and

plural first solder balls on each of said reinforcing pads, each of said plural first solder balls separately attaching the semiconductor device to the circuit board,

wherein said reinforcing pads each have a respective periphery adjacent to each respective one of said plural ones of said first solder balls that has a roundness in line with an outer

~~diameters~~ diameter of said respective first solder ~~balls~~ ball and that, when seen in a plan view of said mounting surface, is at least semicircular, and

wherein each of said reinforcing pads [[are]] is generally X-shaped and [[have]] has four of said first solder balls thereon, each of said four first solder balls being only at a respective distal end thereof.

14. (currently amended) A semiconductor device having a mounting surface attached to a circuit board, the device comprising:

plural reinforcing pads on said mounting surface of said semiconductor device that are each adjacent to a respective corner of said mounting surface; and

plural first solder balls on each of said reinforcing pads, each of said plural first solder balls separately attaching the semiconductor device to the circuit board,

wherein said reinforcing pads each have a respective periphery adjacent to each respective one of said plural ~~ones~~ of said first solder balls that has a roundness in line with an outer ~~diameters~~ diameter of said respective first solder ~~balls~~ ball and that, when seen in a plan view of said mounting surface, is at least semicircular, and

wherein each of said reinforcing pads [[are]] is generally V-shaped and [[have]] has at least two of said first

solder balls thereon, each of said at least two first solder balls being only at a respective distal end thereof.